Title (en)

JUNCTION BETWEEN A MICROSTRIP LINE AND A WAVEGUIDE

Title (de)

ÜBERGANG ZWISCHEN EINER MIKROSTREIFENLEITUNG UND EINEM HOHLLEITER

Title (fr)

JONCTION ENTRE UNE MICROBANDE ET UN GUIDE D'ONDES

Publication

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Application

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Priority

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Abstract (en)

[origin: DE10243671B3] The arrangement has a microstrip conductor on the upper side of a substrate and a hollow conductor on the upper side with an opening and a stepped structure on a side wall near the opening connected to the microstrip conductor. One hollow conductor side wall is a metallised coating on the substrate with an opening into which the microstrip conductor protrudes. Through contacting is arranged between rear metallisation and the metallised coating. The arrangement has a microstrip conductor (ML) on the upper side of a substrate and a hollow conductor on the upper side of the substrate with an opening and stepped structure (ST) on a side wall near the opening connected to the microstrip conductor, whereby one side wall of the hollow conductor is a metallised coating (LS) on the substrate with an opening into which the microstrip conductor protrudes. Through contacting (VH) is arranged between rear side metallisation (RM) enclosing the opening and the metallised coating on the upper side.

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